



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

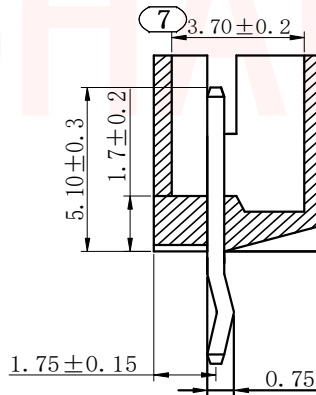
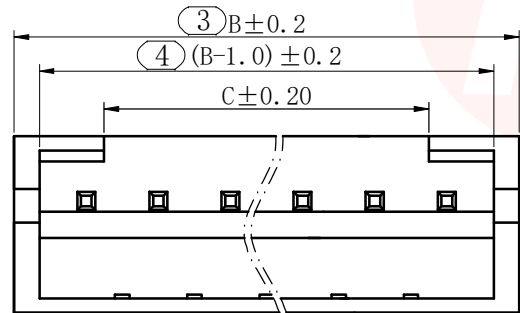
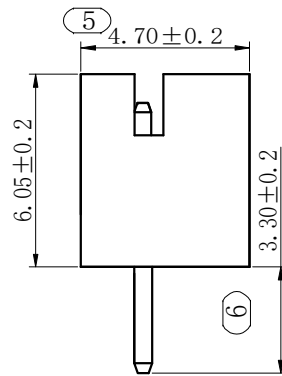
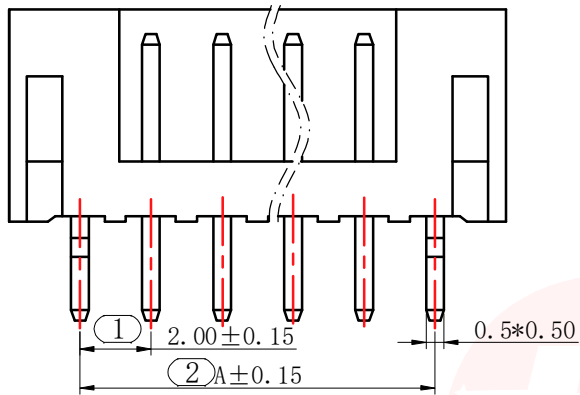
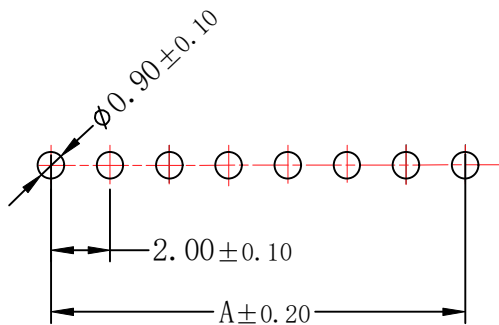


TABLE:

CSG PART NO.	Dimension mm		
	PIN	A	B
WAFER-PH200Z-2A	2P	2.00	6.00
WAFER-PH200Z-3A	3P	4.00	8.00
WAFER-PH200Z-4A	4P	6.00	10.00
WAFER-PH200Z-5A	5P	8.00	12.00
WAFER-PH200Z-6A	6P	10.00	14.00
WAFER-PH200Z-7A	7P	12.00	16.00
WAFER-PH200Z-8A	8P	14.00	18.00
WAFER-PH200Z-9A	9P	16.00	20.00
WAFER-PH200Z-10A	10P	18.00	22.00
WAFER-PH200Z-11A	11P	20.00	24.00
WAFER-PH200Z-12A	12P	22.00	26.00
WAFER-PH200Z-20A	20P	38.00	44.00



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

技术要求:

- 1、塑件材料: PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻:  $\leq 10\text{m}\Omega$
- 4、绝缘电阻:  $\geq 1000\text{M}\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度:  $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235_{-0}^{+5}$ , 时间 $2.5 \pm 0.5$ 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

序号	名称	材料	电镀 (锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	白色
2	基座/Wafer	PA66 (UL94V-0)	白色
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS: X :±0.20 X.X :±0.10 X.XX :±0.05		TITLE: WAFER PH 2.00MM 直针 DIP TYPE DWN: xiong PART NO. WAFER-PH200Z-NA CHKD: lee SCALE:1:1 UNIT: mm APVD: wang SIZE: A4 SHEET:1OF 1 REV: A4	
CUSTOMER COPY			